



DATA SHEET NexSil 6000

NexSil 6000 Silicon Wafer Polishing Slurry

PRODUCT DESCRIPTION

NexSil 6000 silicon wafer polishing slurry is designed for polishing silicon wafers, providing high polishing rates and excellent surface finish. The product is diluted 15:1 or 20:1 depending on the polishing step.

TYPICAL PROPERTIES

Appearance:	Milky White
SiO ₂ Content, %	39 – 41
Na ₂ O Content, %:	0.05 – 0.3
Particle Size, nm:	120
Specific Surface Area, m ² /g:	30 – 60
pH:	11
Viscosity, cP:	3 – 20
Surface Charge:	Negative

TYPICAL POLISHING PERFORMANCE

The following table contains data on typical polishing performance to be expected from NexSil 6000. pH is adjusted using dilute KOH or NaOH after dilution.

TYPICAL STOCK REMOVAL RATE MICRONS/MIN	PRESSURE ON WAFER PSI	PAD TEMPERATURE °C	VOLUME DILUTION	pH	PAD TYPE	WAFER TYPE
3.0–3.5	14	55–60	15:1	11.0	Suba 500	P-Type
1.7–2.0	7	55–60	15:1	11.0	Suba 500	P-Type
0.6–0.9	3	55–60	15:1	11.0	Suba 500	P-Type
FINAL POLISHING STEP: 3 Minutes	4	35–40	20:1	10.5	Politex Supreme	P-Type

FOR ADDITIONAL INFORMATION OR TO ORDER MATERIAL

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